

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	20	V
Gate-Source Voltage		V _{GSS}	±10	V
Drain Current Per Element (Note 5)	Continuous Pulsed (Note 6)	ID	300 350	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	PD	400	mW
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	231	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

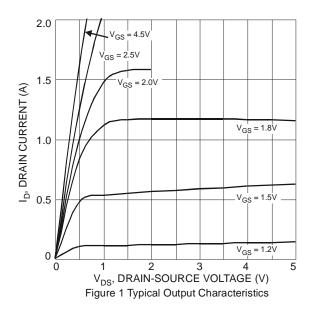
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

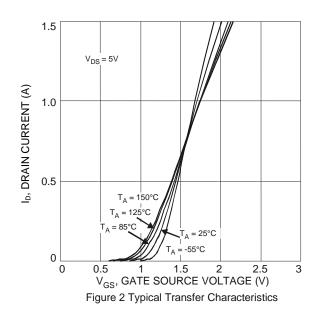
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Per Element) (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	_		V	$V_{GS} = 0V, I_D = 100 \mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	10	μA	$V_{DS} = 17V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}			±5	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Per Element) (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.53		0.9	V	$V_{DS} = V_{GS}, I_{D} = 100 \mu A$
		_	0.35	1.5		$V_{GS} = 4V$, $I_D = 10mA$
			0.4	1.7		$V_{GS} = 2.7V, I_D = 200mA$
Static Drain-Source On-Resistance	R _{DS(ON)}		0.45	1.7	Ω	$V_{GS} = 2.5V, I_D = 10mA$
		_	0.55	3.5		V _{GS} = 1.8V, I _D = 200mA
			0.65	3.5		$V_{GS} = 1.5V, I_D = 1mA$
Forward Transfer Admittance	Y _{fs}	40		_	mS	$V_{DS} = 3V, I_{D} = 10mA$

Notes: 5. Device mounted on FR-4 PCB.

6. Pulse width \leq 10µS, Duty Cycle \leq 1%.

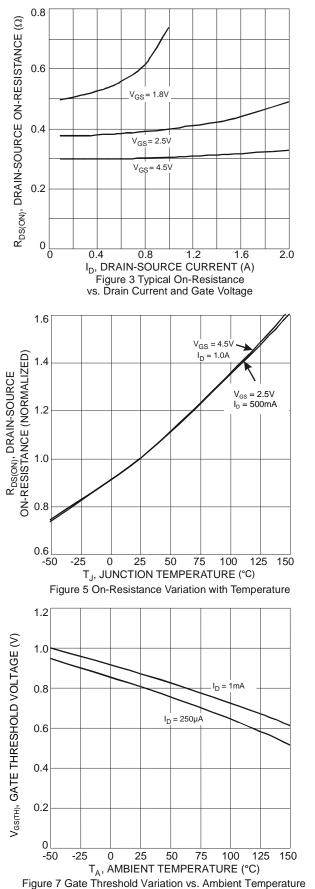
7. Short duration pulse test used to minimize self-heating effect.

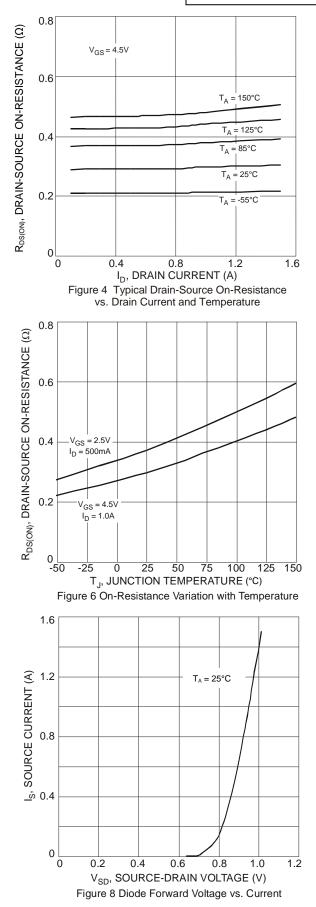




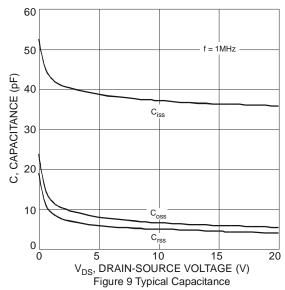


DMN2005DLP4K





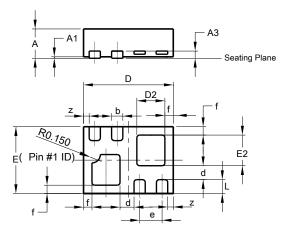




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

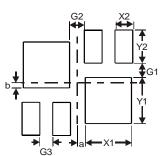
X2-DFN1310-6



X2-DFN1310-6				
Dim	Min	Max	Тур	
Α	-	0.40	-	
A1	0	0.05	0.02	
A3	-	-	0.13	
b	0.10	0.20	0.15	
D	1.25	1.38	1.30	
d	-	-	0.25	
D2	0.30	0.50	0.40	
Е	0.95	1.075	1.00	
e	-	-	0.35	
E2	0.30	0.50	0.40	
f	-	-	0.10	
L	0.20	0.30	0.25	
Z	-	-	0.05	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1310-6

Dimensions	Value (in mm)	
G1	0.16	
G2	0.17	
G3	0.15	
X1	0.52	
X2	0.20	
Y1	0.52	
Y2	0.375	
а	0.09	
b	0.06	



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